

Surface Prep XD Atmospheric Plasma System

DATA SHEET

Safe, clean, cost effective solution for non-contact surface activation & cleaning prior to bonding, coating & printing

True multi gas capabilityensures low cost of ownership and simple facility installation.

Use your facility compressed air - no special filtering required - or other gases such as O_2 , N_2 , Ar or CO_2 – providing the flexibility to create the exact reactive species needed to achieve your desired surface modification needs:

- Clean
- Mico-etch
- Activate / Wet
- Functionalize
- Deposit



Works on both conductive and non-conductive materials. Low temperature plasma is safe on sensitive polymers, thin films and glass. Treat stainless steel, Ti, NiTi, Au and other metals as well as these polymers:

- Pebax
- PEEK
- Nylons
- Polyimide
- Silicone
- HDPE / LDPE
- PET
- PVC
- Polypropylene
- Silicone
- PDMS



Plasma treat any form factor from 2D flat surfaces to complex 3D MEMS and micro fluidics. Typical applications include guide wire coating, catheter bonding & coating, electronics encapsulation, lab on chip, biotech – any Advanced Material Interface challenge.

Free your process from dangerous wet chemistry or dirty abrasive surface preparation methods. Try our safe, high speed atmospheric plasma solutions today.



EQUIPMENT SPECIFICATIONS

Item	UNIT	Specification
Input Power	Volt	220
Input Frequency	Hz	50/60
Input Current	Amp	6
Output Voltage	KVolt	Max 18 KV
Output Frequency	KHz	Max 50
Output Current	Amp	0.3
Max. Ambient Temperature and	Deg.C	60
Humidity for Continuous Operation		
Discharge Head	Ea	1
Dimension	mm (WHD)	480mm x 240 x 210
Weight	Kg	14
Shipping Weight	Kg	23







SurfacePrep XD systems require either compressed air supply from a clean, dry source or bottled gas such as oxygen, nitrogen, argon or CO2. "Welding Grade A" purity is acceptable – ultra high purity not required.

Gas supply is connected to the 8mm tube fitting on the back of the power supply and is required to be regulated between 0.15 MPa to 0.30 Mpa.

ADVANCED MATERIAL INTERFACE SOLUTIONS